

RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1620	D1	MAR '01	26780	0106	CPS (ChipPac, China)	DH045040AA	SOIC	50	50	0
DS1620	D1	JUN '01	27096	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	50	50	0
DS1620	D1	SEP '01	27862	0111	NSEB	DJ051232AAI	SOIC	50	50	0
DS1869	A3	JUN '00	25547	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	25	48	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C5	JAN '01	26506	0047 ATK (Amkor, K)	DN028766AAD	MQFP	3	203	0
DS5002	C5	APR '01	26899	0112 ATK (Amkor, K)	DN030363AAA	MQFP	3	203	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	JUL '01	27336	0105	ATP (Amkor, PI)	DK046225AB	SOIC	4	0
DS1232	C2-L	APR '01	26861	0105	OSEP	DE045054ABB	SOIC	4	0
DS1233	A5	APR '01	26868	0101	Fastech	DA048537AF	SOT223	4	0
DS1233	A5	JUL '01	27349	0110	Carsem	DM048543AA	SOT223	4	0
DS1233	A5	OCT '01	28003	0128	Fastech	DA102602AC	SOT223	4	0
DS1267	A1	MAY '01	26976	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	4	0
DS1620	D1	MAR '01	26773	0106	CPS (ChipPac, China)	DH045040AA	SOIC	4	0
DS1620	D1	JUN '01	27090	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	4	0
DS1620	D1	SEP '01	27856	0111	NSEB	DJ051232AAI	SOIC	4	0
DS1803	A2	FEB '01	26606	0105	OSEP	DE047362AAB	SOIC	4	0
DS1803	A2	MAY '01	26990	0115	Carsem	DM052456AC	SOIC	4	0
DS1869	A3	JUN '00	25540	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	4	0
DS2118M	B1	JUN '01	27111	0117	ATK (Amkor, K)	DN101149AAD	SSOP	4	0
DS21352	A4	JUN '01	27343	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	4	0
DS2154	A2	MAR '01	26759	0106	ATK (Amkor, K)	DN040708AA-	LQFP	4	0
DS2154	A2	JUN '01	27098	0107	Stats	DC040702AA-	LQFP	4	0
DS2154	A2	SEP '01	27838	0125	ATK (Amkor, K)	DN104641AA-	LQFP	4	0
DS2175	D1	JAN '01	26419	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	4	0
DS2175	D1	APR '01	26880	0050	ATP (Amkor, PI)	DK036683AB	SOIC	4	0
DS21Q43	A3-A	DEC '00	26366	0034	ATK (Amkor, K)	DN027568AAC	LQFP	4	0
DS21Q43	A3-A	SEP '01	27877	0047	Stats	DC036714AAD	LQFP	4	0
DS21S07	C1-	FEB '01	26584	0047	Carsem	DM035532AF	TSSOP	4	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS2502	C4	APR '01	26914	0107 OSEP	DE041143AKA	TSOC	4 0
DS2502	C4	JUL '01	27372	0125 OSEP	DE052527ACA	TSOC	4 0
DS5002	C5	JAN '01	26505	0047 ATK (Amkor, K)	DN028766AAD	MQFP	4 0
DS5002	C5	APR '01	26898	0112 ATK (Amkor, K)	DN030363AAA	MQFP	4 0
DS5002	C6	JUL '01	27361	0122 ATK (Amkor, K)	DN042297AAA	MQFP	4 0
DS80CH11	A4	MAR '01	26782	0103 ATK (Amkor, K)	DN029182AAA	LQFP	4 0
DS80CH11	A4	JUN '01	27104	0108 ATK (Amkor, K)	DN034351AA	LQFP	4 0
DS80CH11	A4	SEP '01	27864	0110 Stats	DC037148AA	LQFP	4 0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	A1-Y	APR '01	26859	0101	Fastech	300896	Module w/SMT	300	100	3
DS1230	A1-Y	JUL '01	27334	0119	Fastech	302244	Module w/SMT	300	99	1
DS12887	A2-	JAN '01	26451	0043	Fastech	300511	Module w/Bent Fra	300	100	0
DS12887	A2-	APR '01	26878	0102	Fastech	301097	Module w/Bent Fra	300	100	0
DS12887	A2-	JUL '01	27359	0121	Fastech	302296	Module w/Bent Fra	300	100	0
DS12887	A2-	OCT '01	28013	0137	Fastech	303363	Module w/Bent Fra	300	100	0
DS1644	B2	& DS9034	26628	0051	Fastech	300700	Power Cap	300	77	0
DS1992	E7	JUN '01	27088	0122	Dallas	DS044720ABR	iButton F50 w/Bum	300	77	0
DS1992	E7	SEP '01	27836	0136	Dallas	DB109491AA	iButton F50 w/Bum	300	77	0
DS29020	A7-3	JUN '01	27165	0158	Dallas	DX043531AEA	Cartridge	300	77	0
DS3816	A-C	& DS3801	26617	0105	Dallas	305696	BGA Module	300	33	0
DS3816	A-C	& DS3801	26617	0105	Dallas	305696	BGA Module	1000	22	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27340	0105	ATP (Amkor, PI)	DK046225AB	SOIC	300	40	0
DS1232	C2-L	JUL '01	27340	0105	ATP (Amkor, PI)	DK046225AB	SOIC	1000	40	0
DS1232	C2-L	APR '01	26865	0105	OSEP	DE045054ABB	SOIC	300	40	1
DS1232	C2-L	APR '01	26865	0105	OSEP	DE045054ABB	SOIC	1000	39	0
DS1233	A5	APR '01	26872	0101	Fastech	DA048537AF	SOT223	700	40	11
DS1233	A5	JUL '01	27353	0110	Carsem	DM048543AA	SOT223	700	40	0
DS1233	A5	OCT '01	28007	0128	Fastech	DA102602AC	SOT223	700	40	0
DS1267	A1	MAY '01	26980	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	300	35	0
DS1302	A3	DEC '00	26334	0032	CPS (ChipPac, China)	DH028629AB	PDIP	300	40	0
DS1302	A3	DEC '00	26334	0032	CPS (ChipPac, China)	DH028629AB	PDIP	1000	40	0
DS1302	A3	MAR '01	26751	0105	CPS (ChipPac, China)	DH036622AB	PDIP	300	40	0
DS1302	A3	MAR '01	26751	0105	CPS (ChipPac, China)	DH036622AB	PDIP	1000	40	0
DS1620	D1	JUN '01	27094	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	300	40	0
DS1620	D1	JUN '01	27094	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	1000	40	0
DS1620	D1	SEP '01	27860	0111	NSEB	DJ051232AAI	SOIC	300	40	0
DS1620	D1	SEP '01	27860	0111	NSEB	DJ051232AAI	SOIC	1000	40	0
DS1803	A2	FEB '01	26611	0105	OSEP	DE047362AAB	SOIC	300	40	0
DS1803	A2	FEB '01	26611	0105	OSEP	DE047362AAB	SOIC	1000	34	0
DS1803	A2	MAY '01	26994	0115	Carsem	DM052456AC	SOIC	300	40	0
DS1803	A2	MAY '01	26994	0115	Carsem	DM052456AC	SOIC	1000	31	0
DS1869	A3	JUN '00	25545	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	300	40	0
DS1869	A3	JUN '00	25545	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	1000	40	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2118M	B1	JUN '01	27115	0117	ATK (Amkor, K)	DN101149AAD	SSOP	300	80	0
DS2118M	B1	JUN '01	27115	0117	ATK (Amkor, K)	DN101149AAD	SSOP	1000	80	0
DS21352	A4	JUN '01	27347	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	300	80	0
DS21352	A4	JUN '01	27347	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	1000	79	0
DS2154	A2	MAR '01	26764	0106	ATK (Amkor, K)	DN040708AA-	LQFP	300	80	0
DS2154	A2	MAR '01	26764	0106	ATK (Amkor, K)	DN040708AA-	LQFP	1000	80	0
DS2154	A2	JUN '01	27102	0107	Stats	DC040702AA-	LQFP	300	80	0
DS2154	A2	JUN '01	27102	0107	Stats	DC040702AA-	LQFP	1000	80	0
DS2154	A2	SEP '01	27842	0125	ATK (Amkor, K)	DN104641AA-	LQFP	300	80	0
DS2175	D1	JAN '01	26424	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	300	40	0
DS2175	D1	JAN '01	26424	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	1000	40	0
DS2175	D1	APR '01	26884	0050	ATP (Amkor, PI)	DK036683AB	SOIC	300	40	0
DS2175	D1	APR '01	26884	0050	ATP (Amkor, PI)	DK036683AB	SOIC	1000	40	0
DS21Q43	A3-A	DEC '00	26371	0034	ATK (Amkor, K)	DN027568AAC	LQFP	300	70	0
DS21Q43	A3-A	DEC '00	26371	0034	ATK (Amkor, K)	DN027568AAC	LQFP	1000	70	0
DS21S07	C1-	FEB '01	26589	0047	Carsem	DM035532AF	TSSOP	300	40	0
DS21S07	C1-	FEB '01	26589	0047	Carsem	DM035532AF	TSSOP	1000	40	0
DS2401	C2	SEP '01	27885	0130	Fastech	DA033008AJ	TO92	300	40	0
DS2401	C2	SEP '01	27885	0130	Fastech	DA033008AJ	TO92	1000	40	0
DS2502	C4	APR '01	26917	0107	OSEP	DE041143AKA	TSOC	300	77	0
DS2502	C4	APR '01	26917	0107	OSEP	DE041143AKA	TSOC	1000	77	0
DS2502	C4	JUL '01	27375	0125	OSEP	DE052527ACA	TSOC	300	77	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	JUL '01	27375	0125 OSEP	DE052527ACA	TSOC	1000	77	0
DS5002	C5	JAN '01	26510	0047 ATK (Amkor, K)	DN028766AAD	MQFP	300	40	0
DS5002	C5	JAN '01	26510	0047 ATK (Amkor, K)	DN028766AAD	MQFP	1000	40	0
DS5002	C5	APR '01	26902	0112 ATK (Amkor, K)	DN030363AAA	MQFP	300	40	0
DS5002	C5	APR '01	26902	0112 ATK (Amkor, K)	DN030363AAA	MQFP	1000	40	0
DS5002	C6	JUL '01	27365	0122 ATK (Amkor, K)	DN042297AAA	MQFP	300	40	0
DS5002	C6	JUL '01	27365	0122 ATK (Amkor, K)	DN042297AAA	MQFP	1000	40	0
DS80CH11	A4	MAR '01	26787	0103 ATK (Amkor, K)	DN029182AAA	LQFP	300	70	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '01	26430	0045 Fastech	305435	Module w/SMT	300	100	0
DS1230	A1-Y	JAN '01	26430	0045 Fastech	305435	Module w/SMT	1000	100	0
DS1643	C1	FEB '01	26566	0104 Fastech	301297	Module w/Hi Densit	300	77	0
DS1643	C1	FEB '01	26566	0104 Fastech	301297	Module w/Hi Densit	1000	77	0
DS3816	A-C	& DS3801	26054	0041 Dallas	120701	BGA Module	300	33	0
DS3816	A-C	& DS3801	26054	0041 Dallas	120701	BGA Module	1000	28	0
DS3816	A-C	& DS3801	26054	0041 Dallas	120701	BGA Module	2000	25	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1620	D1	MAR '01	26781	0106	CPS (ChipPac, China)	DH045040AA	SOIC	336	50	0
DS1620	D1	MAR '01	26781	0106	CPS (ChipPac, China)	DH045040AA	SOIC	1000	50	0
DS1620	D1	JUN '01	27097	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	336	50	0
DS1620	D1	JUN '01	27097	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	1000	50	0
DS1869	A3	JUN '00	25547	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	336	46	0
DS1869	A3	JUN '00	25547	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	1000	46	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '01	26565	0104 Fastech	301297	Module w/Hi Densit	336	77	0
DS1643	C1	FEB '01	26565	0104 Fastech	301297	Module w/Hi Densit	1000	77	0
DS1644	B2	& DS9034	26627	0051 Fastech	300700	Power Cap	336	71	1
DS1644	B2	& DS9034	26627	0051 Fastech	300700	Power Cap	1000	69	0
DS1992	E7	JUN '01	27087	0122 Dallas	DS044720ABR	iButton F50 w/Bum	336	77	0
DS1992	E7	JUN '01	27087	0122 Dallas	DS044720ABR	iButton F50 w/Bum	1000	77	0
DS1992	E7	SEP '01	27835	0136 Dallas	DB109491AA	iButton F50 w/Bum	336	77	0
DS1992	E7	SEP '01	27835	0136 Dallas	DB109491AA	iButton F50 w/Bum	1000	77	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '01	26429	0045 Fastech	305435	Module w/SMT	48	200	0
DS1230	A1-Y	APR '01	26858	0101 Fastech	300896	Module w/SMT	48	200	0
DS1230	A1-Y	JUL '01	27333	0119 Fastech	302244	Module w/SMT	48	200	1
DS29020	A7-3	JUN '01	27164	0158 Dallas	DX043531AEA	Cartridge	336	77	0
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module	336	33	0
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module	1000	30	1
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module	2000	29	0
DS3816	A-C	& DS3801	26616	0105 Dallas	305696	BGA Module	336	33	0
DS3816	A-C	& DS3801	26616	0105 Dallas	305696	BGA Module	1000	30	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: JESD22-B102

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1230	A1-Y	JUL '01	27331	0119 Fastech	302244	Module w/SMT	3 0
DS12887	A2-	JUL '01	27356	0121 Fastech	302296	Module w/Bent Fra	3 0
DS12887	A2-	OCT '01	28010	0137 Fastech	303363	Module w/Bent Fra	3 0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1230	A1-Y	JAN '01	26427	0045	Fastech	305435	Module w/SMT	3	0
DS1230	A1-Y	APR '01	26856	0101	Fastech	300896	Module w/SMT	3	0
DS12887	A2-	JAN '01	26448	0043	Fastech	300511	Module w/Bent Fra	3	0
DS12887	A2-	APR '01	26875	0102	Fastech	301097	Module w/Bent Fra	3	0
DS1643	C1	FEB '01	26563	0104	Fastech	301297	Module w/Hi Densit	3	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	
		DATE	JOB NO					CODE	FACILITY
DS1232	C2-L	JUL '01	27338	0105	ATP (Amkor, PI)	DK046225AB	SOIC	4	0
DS1232	C2-L	APR '01	26863	0105	OSEP	DE045054ABB	SOIC	4	0
DS1267	A1	MAY '01	26978	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	4	0
DS1620	D1	MAR '01	26775	0106	CPS (ChipPac, China)	DH045040AA	SOIC	4	0
DS1620	D1	JUN '01	27092	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	4	0
DS1620	D1	SEP '01	27858	0111	NSEB	DJ051232AAI	SOIC	4	0
DS1803	A2	FEB '01	26608	0105	OSEP	DE047362AAB	SOIC	4	0
DS1869	A3	JUN '00	25542	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	4	0
DS2118M	B1	JUN '01	27113	0117	ATK (Amkor, K)	DN101149AAD	SSOP	4	0
DS21352	A4	JUN '01	27345	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	4	0
DS2154	A2	MAR '01	26761	0106	ATK (Amkor, K)	DN040708AA-	LQFP	4	0
DS2154	A2	JUN '01	27100	0107	Stats	DC040702AA-	LQFP	4	0
DS2154	A2	SEP '01	27840	0125	ATK (Amkor, K)	DN104641AA-	LQFP	4	0
DS2175	D1	JAN '01	26421	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	4	0
DS2175	D1	APR '01	26882	0050	ATP (Amkor, PI)	DK036683AB	SOIC	4	0
DS21Q43	A3-A	DEC '00	26368	0034	ATK (Amkor, K)	DN027568AAC	LQFP	4	0
DS21S07	C1-	FEB '01	26586	0047	Carsem	DM035532AF	TSSOP	4	0
DS2502	C4	APR '01	26916	0107	OSEP	DE041143AKA	TSOC	4	0
DS2502	C4	JUL '01	27374	0125	OSEP	DE052527ACA	TSOC	4	0
DS5002	C5	JAN '01	26507	0047	ATK (Amkor, K)	DN028766AAD	MQFP	4	0
DS5002	C5	APR '01	26900	0112	ATK (Amkor, K)	DN030363AAA	MQFP	4	0
DS5002	C6	JUL '01	27363	0122	ATK (Amkor, K)	DN042297AAA	MQFP	4	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS80CH11	A4	MAR '01	26784	0103 ATK (Amkor, K)	DN029182AAA	LQFP	4 0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: JESD22-B100

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1230	A1-Y	JUL '01	27332	0119 Fastech	302244	Module w/SMT	6 0
DS12887	A2-	JUL '01	27357	0121 Fastech	302296	Module w/Bent Fra	6 0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1230	A1-Y	JAN '01	26428	0045	Fastech	305435	Module w/SMT	6	0
DS1230	A1-Y	APR '01	26857	0101	Fastech	300896	Module w/SMT	6	0
DS12887	A2-	JAN '01	26449	0043	Fastech	300511	Module w/Bent Fra	6	0
DS12887	A2-	APR '01	26876	0102	Fastech	301097	Module w/Bent Fra	6	0
DS1643	C1	FEB '01	26564	0104	Fastech	301297	Module w/Hi Densit	6	0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	A1-Y	JAN '01	26431	0045	Fastech	305435	Module w/SMT	288	100	0
DS1230	A1-Y	JAN '01	26431	0045	Fastech	305435	Module w/SMT	960	100	4
DS1230	A1-Y	APR '01	26860	0101	Fastech	300896	Module w/SMT	288	100	0
DS1230	A1-Y	APR '01	26860	0101	Fastech	300896	Module w/SMT	960	100	0
DS1230	A1-Y	JUL '01	27335	0119	Fastech	302244	Module w/SMT	288	100	0
DS1230	A1-Y	JUL '01	27335	0119	Fastech	302244	Module w/SMT	960	100	0
DS1644	B2	& DS9034	26629	0051	Fastech	300700	Power Cap	288	77	0
DS1646	B2	OCT '00	26132	0039	Fastech	122182	Module w/Hi Densit	288	77	2
DS1646	B2	JAN '01	26454	0050	Fastech	300710	Module w/Hi Densit	288	77	1
DS1992	E7	JUN '01	27089	0122	Dallas	DS044720ABR	iButton F50 w/Bum	288	77	0
DS1992	E7	JUN '01	27089	0122	Dallas	DS044720ABR	iButton F50 w/Bum	960	77	0
DS1992	E7	SEP '01	27837	0136	Dallas	DB109491AA	iButton F50 w/Bum	288	77	0
DS1992	E7	SEP '01	27837	0136	Dallas	DB109491AA	iButton F50 w/Bum	960	77	0
DS3816	A-C	& DS3801	26055	0041	Dallas	120701	BGA Module	288	33	2
DS3816	A-C	& DS3801	26618	0105	Dallas	305696	BGA Module	288	33	0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 85 C/85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS29020	A7-3	JUN '01	27166	0158	Dallas	DX043531AEA	Cartridge	274	77	0

RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JAN '01	26450	0043 Fastech	300511	Module w/Bent Fra	48	200	0
DS12887	A2-	APR '01	26877	0102 Fastech	301097	Module w/Bent Fra	48	200	0
DS12887	A2-	JUL '01	27358	0121 Fastech	302296	Module w/Bent Fra	48	200	0
DS12887	A2-	OCT '01	28012	0137 Fastech	303363	Module w/Bent Fra	48	200	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21352	A4	JUN '01	27348	0103 ATP (Amkor, PI)	DN033071AAA	LQFP	200	62	0
DS2154	A2	MAR '01	26765	0106 ATK (Amkor, K)	DN040708AA-	LQFP	200	68	0
DS2154	A2	JUN '01	27103	0107 Stats	DC040702AA-	LQFP	200	76	0
DS2154	A2	SEP '01	27843	0125 ATK (Amkor, K)	DN104641AA-	LQFP	200	77	0
DS21Q43	A3-A	DEC '00	26373	0034 ATK (Amkor, K)	DN027568AAC	LQFP	100	36	0
DS80CH11	A4	MAR '01	26789	0103 ATK (Amkor, K)	DN029182AAA	LQFP	100	40	0

RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27341	0105 ATP (Amkor, PI)	DK046225AB	SOIC	100	77	2
DS1232	C2-L	APR '01	26866	0105 OSEP	DE045054ABB	SOIC	88	77	0
DS1233	A5	APR '01	26873	0101 Fastech	DA048537AF	SOT223	100	77	0
DS1233	A5	JUL '01	27354	0110 Carsem	DM048543AA	SOT223	100	77	0
DS1233	A5	OCT '01	28008	0128 Fastech	DA102602AC	SOT223	100	77	0
DS2401	C2	SEP '01	27886	0130 Fastech	DA033008AJ	TO92	100	77	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	& DS9034	26625	0051 Fastech	300700	Power Cap	2	225	0
DS3816	A-C	& DS3801	26051	0041 Dallas	120701	BGA Module	2	99	0
DS3816	A-C	& DS3801	26614	0105 Dallas	305696	BGA Module	2	99	1
DS5002	C6	JUL '01	27362	0122 ATK (Amkor, K)	DN042297AAA	MQFP	3	206	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27337	0105	ATP (Amkor, PI)	DK046225AB	SOIC	3	241	0
DS1232	C2-L	APR '01	26862	0105	OSEP	DE045054ABB	SOIC	3	238	0
DS1233	A5	APR '01	26869	0101	Fastech	DA048537AF	SOT223	3	238	0
DS1233	A5	JUL '01	27350	0110	Carsem	DM048543AA	SOT223	3	241	0
DS1233	A5	OCT '01	28004	0128	Fastech	DA102602AC	SOT223	3	241	1
DS1267	A1	MAY '01	26977	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	3	238	0
DS1620	D1	MAR '01	26774	0106	CPS (ChipPac, China)	DH045040AA	SOIC	3	241	0
DS1620	D1	JUN '01	27091	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	3	241	0
DS1620	D1	SEP '01	27857	0111	NSEB	DJ051232AAI	SOIC	3	244	0
DS1803	A2	FEB '01	26607	0105	OSEP	DE047362AAB	SOIC	3	238	0
DS1803	A2	MAY '01	26991	0115	Carsem	DM052456AC	SOIC	3	238	0
DS1869	A3	JUN '00	25541	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	3	241	0
DS2118M	B1	JUN '01	27112	0117	ATK (Amkor, K)	DN101149AAD	SSOP	3	238	0
DS21352	A4	JUN '01	27344	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	3	238	5
DS2154	A2	MAR '01	26760	0106	ATK (Amkor, K)	DN040708AA-	LQFP	3	238	0
DS2154	A2	JUN '01	27099	0107	Stats	DC040702AA-	LQFP	3	238	0
DS2154	A2	SEP '01	27839	0125	ATK (Amkor, K)	DN104641AA-	LQFP	3	241	0
DS2175	D1	JAN '01	26420	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	3	238	0
DS2175	D1	APR '01	26881	0050	ATP (Amkor, PI)	DK036683AB	SOIC	3	238	0
DS21Q43	A3-A	DEC '00	26367	0034	ATK (Amkor, K)	DN027568AAC	LQFP	3	239	0
DS21Q43	A3-A	SEP '01	27878	0047	Stats	DC036714AAD	LQFP	3	241	0
DS21S07	C1-	FEB '01	26585	0047	Carsem	DM035532AF	TSSOP	3	238	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	APR '01	26915	0107 OSEP	DE041143AKA	TSOC	3	151	0
DS2502	C4	JUL '01	27373	0125 OSEP	DE052527ACA	TSOC	3	151	0
DS80CH11	A4	JUN '01	27105	0108 ATK (Amkor, K)	DN034351AA	LQFP	3	239	0
DS80CH11	A4	SEP '01	27865	0110 Stats	DC037148AA	LQFP	3	242	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1267	A1	MAY '01	26981	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	274	75	0
DS12887	A2-	JAN '01	26452	0043	Fastech	300511	Module w/Bent Fra	274	100	0
DS12887	A2-	JAN '01	26452	0043	Fastech	300511	Module w/Bent Fra	959	96	0
DS12887	A2-	APR '01	26879	0102	Fastech	301097	Module w/Bent Fra	274	100	1
DS12887	A2-	APR '01	26879	0102	Fastech	301097	Module w/Bent Fra	959	99	0
DS12887	A2-	JUL '01	27360	0121	Fastech	302296	Module w/Bent Fra	274	100	0
DS12887	A2-	JUL '01	27360	0121	Fastech	302296	Module w/Bent Fra	959	100	0
DS12887	A2-	OCT '01	28014	0137	Fastech	303363	Module w/Bent Fra	274	99	0
DS12887	A2-	OCT '01	28014	0137	Fastech	303363	Module w/Bent Fra	959	99	0
DS1302	A3	DEC '00	26335	0032	CPS (ChipPac, China)	DH028629AB	PDIP	274	77	0
DS1302	A3	DEC '00	26335	0032	CPS (ChipPac, China)	DH028629AB	PDIP	959	77	0
DS1302	A3	MAR '01	26752	0105	CPS (ChipPac, China)	DH036622AB	PDIP	274	77	0
DS1302	A3	MAR '01	26752	0105	CPS (ChipPac, China)	DH036622AB	PDIP	959	77	0
DS1620	D1	JUN '01	27095	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	274	70	1
DS1620	D1	JUN '01	27095	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	959	69	0
DS1620	D1	SEP '01	27861	0111	NSEB	DJ051232AAI	SOIC	274	70	0
DS1620	D1	SEP '01	27861	0111	NSEB	DJ051232AAI	SOIC	959	70	0
DS1803	A2	FEB '01	26612	0105	OSEP	DE047362AAB	SOIC	274	77	0
DS1803	A2	MAY '01	26995	0115	Carsem	DM052456AC	SOIC	274	77	0
DS1869	A3	JUN '00	25546	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	274	70	0
DS1869	A3	JUN '00	25546	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	959	69	0
DS2175	D1	JAN '01	26425	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	274	77	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2175	D1	JAN '01	26425	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	959	77	0
DS2175	D1	APR '01	26885	0050	ATP (Amkor, PI)	DK036683AB	SOIC	274	77	0
DS21Q43	A3-A	DEC '00	26372	0034	ATK (Amkor, K)	DN027568AAC	LQFP	274	31	0
DS21Q43	A3-A	DEC '00	26372	0034	ATK (Amkor, K)	DN027568AAC	LQFP	959	31	0
DS21S07	C1-	FEB '01	26590	0047	Carsem	DM035532AF	TSSOP	274	77	0
DS21S07	C1-	FEB '01	26590	0047	Carsem	DM035532AF	TSSOP	959	77	0
DS5002	C5	JAN '01	26511	0047	ATK (Amkor, K)	DN028766AAD	MQFP	274	42	0
DS5002	C5	JAN '01	26511	0047	ATK (Amkor, K)	DN028766AAD	MQFP	959	41	0
DS5002	C5	APR '01	26903	0112	ATK (Amkor, K)	DN030363AAA	MQFP	274	42	0
DS5002	C5	APR '01	26903	0112	ATK (Amkor, K)	DN030363AAA	MQFP	959	42	0
DS5002	C6	JUL '01	27366	0122	ATK (Amkor, K)	DN042297AAA	MQFP	274	42	0
DS5002	C6	JUL '01	27366	0122	ATK (Amkor, K)	DN042297AAA	MQFP	959	41	0
DS80CH11	A4	MAR '01	26788	0103	ATK (Amkor, K)	DN029182AAA	LQFP	274	48	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27342	0105	ATP (Amkor, PI)	DK046225AB	SOIC	96	39	0
DS1232	C2-L	APR '01	26867	0105	OSEP	DE045054ABB	SOIC	96	40	0
DS1233	A5	APR '01	26874	0101	Fastech	DA048537AF	SOT223	96	40	0
DS1233	A5	JUL '01	27355	0110	Carsem	DM048543AA	SOT223	96	40	0
DS1233	A5	OCT '01	28009	0128	Fastech	DA102602AC	SOT223	96	40	0
DS1267	A1	MAY '01	26982	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	96	34	0
DS1803	A2	FEB '01	26613	0105	OSEP	DE047362AAB	SOIC	96	30	0
DS1803	A2	MAY '01	26996	0115	Carsem	DM052456AC	SOIC	96	37	0
DS2118M	B1	JUN '01	27116	0117	ATK (Amkor, K)	DN101149AAD	SSOP	96	77	0
DS2175	D1	JAN '01	26426	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	96	39	0
DS2175	D1	APR '01	26886	0050	ATP (Amkor, PI)	DK036683AB	SOIC	96	40	0
DS21S07	C1-	FEB '01	26591	0047	Carsem	DM035532AF	TSSOP	96	36	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1302	A3	DEC '00	26336	0032 CPS (ChipPac, China)	DH028629AB	PDIP	96	38	0
DS1302	A3	MAR '01	26753	0105 CPS (ChipPac, China)	DH036622AB	PDIP	96	40	0
DS2401	C2	SEP '01	27887	0130 Fastech	DA033008AJ	TO92	96	40	0
DS2502	C4	APR '01	26918	0107 OSEP	DE041143AKA	TSOC	96	70	0
DS2502	C4	JUL '01	27376	0125 OSEP	DE052527ACA	TSOC	96	70	0
DS5002	C5	JAN '01	26512	0047 ATK (Amkor, K)	DN028766AAD	MQFP	96	37	0
DS5002	C5	APR '01	26904	0112 ATK (Amkor, K)	DN030363AAA	MQFP	96	39	0
DS5002	C6	JUL '01	27367	0122 ATK (Amkor, K)	DN042297AAA	MQFP	96	40	0

RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	& DS9034	26626	0051	Fastech	300700	Power Cap	2	230	5